2008 SW Test Workshop Preliminary Agenda and Technical Program

The Technical Program and Conference Agenda are subject to change without notice.

	SUNDAY (June 8, 2008)	MONDAY (June 9, 2008)	TUESDAY (June 10, 2008)	WEDNESDAY (June 11, 2008)
7:00 AM 7:30 AM		**REGISTRATION AND CONTINENTAL BREAKFAST** (700 to 800AM)	**CONTINENTAL BREAKFAST** (700 to 800AM)	**CONTINENTAL BREAKFAST** (700 to 800AM)
8:00 AM		**WELCOME (800 to 830AM)** Welcome to SW Test 2008 *Jerry Broz, Ph.D. (SW Test General Chair)*	**Large Array Probing (800 to 1000AM)** Challenges of 300mm Probe *John Strom (Rudolph Technologies)*	**Strategic Design Methodologies (800 to 1000AM)** Design for Probe Ramp Review *E Boyd Daniels, Bret Stewart, Norm Armendariz (Texas Instruments)*
8:30 AM		**MEMS for Production-Level Probing (830 TO 1000AM)** Novel Method to Store Spring Energy in Probes *Salleh Ismail, Ph.D. (Touch Down Technologies)*	40k Probes on 300mm Probe Card - another step towards 1 touchdown DRAM SORT *Michael Huebner, Ph.D. (FormFactor)*	Probe Card Operations in the Global Environment *Manish Gulati (FormFactor), Alan Romreill (Spansion)*
9:00 AM		Mechanical Design of MEMS Probes for Wafer Test *Chris Folk, Ph.D. (Microfabrica)*	Electrical Planarity Characterization of High Parallelism Probe Cards *John Caldwell (Micron Technology)*	Tangible value can be Realized by Standardizing Probe Interfaces *Keith Imai (Semiconductor Test Consortium)*
9:30 AM		*MicroProbe Vx-MP Probe Card Technology* *January Kister, Steve Hopkins (MicroProbe)*	High-Performance Contactors for Wafer-Scale Test *Jim Brandes (Everett Charles Technologies)*	Accelerating CAD design of Probe Cards using Allegro System Architect *S. Dharmarajan (Cadence)*
10:00 AM		**BREAK (1000 to 1030AM)**	**BREAK (1000 to 1030AM)**	**BREAK (1000 to 1030AM)**
10:30 AM		**Advances in Traditional Probe Card Technologies (1030AM to Noon)** Probing of POA Power Devices: A new epoxy probe card technology development *Raffaele Vallauri, et al. (STMicroelectronics), Stefano Lazzari, et al. (Technoprobe)*	**Probe Potpourri** **(1030AM to Noon)** Comparison of Drilling Rates and Tolerances of Laser-Drilled holes in Silicon Nitride and Polyimide Vertical Probe Cards *Alan Ferguson, Ph.D., Martyn Knowles, Ph.D. (Oxford Laser)*	**Probe Challenges** **(1030AM to Noon)** Effect of Parasitics in Signal and Ground Path on Timing Accuracy *Gert Hohenwarter (Gatewave Northern)*
11:00 AM		Vertical Probe Alternative for Cantilever Pad Probing *Robert Doherty (Analog Devices), Robert Rogers (Wentworth Labs)*	Non-contact Test at Advanced Process Nodes *Chris Sellathamby, Ph.D., Brian Moore, Jeff Hintzke (Scanemetrics)*	Overcoming the Challenges of Parallel RF Test *Roger Hayward, Jeff Arasmith (Cascade Microtech)*
11:30 AM		Automatic Probe Assembling Machine *Dave Oh, Justin Yun (TSE)*	CO2 Composite Spray Cleaning Technology for Probe Card Cleaning *David P. Jackson (Cool Clean Technologies)*	An Advanced Cantilever Probe Card with High Frequency Bandwidth (>3GHz) *Morgan Ku, Phil Hsieh, Jason Ho, Sobers Chang, Seenew Lai (MJC Probe Inc.)*
12:00 PM		**LUNCH (Noon to 100PM)**	**LUNCH (Noon to 100PM)**	**AWARDS and FAREWELL LUNCHEON (Noon to 100PM)**
12:30 PM			**Paradise Lawn (BBQ)**	
1:00 PM		**Improving Test Cell Performance (100 to 300PM)** Mechanical Simulation of Probing on SMART POWER POA Devices *Luca Cecchetto, et al. (ST Microelectronics), Stefano Lazzari, et al. (Technoprobe)*	**Probe Card Cleaning Practices (100PM to 300PM)** Probe Card Cleaning Media Survey *Eric Hill, Josh Smith (Cascade Microtech)*	
1:30 PM		Use of On-Line Probe-to-Pad-Alignment (PTPA) Data to Improve Test Cell Performance *Ernesto Cornejo (Micron Technology)*	Methodologies for Assessing On-line Probe Process Parameters *Jan Martens (NXP Semiconductors), Simon Allgaier (Feinmetall), Jerry Broz, Ph.D. (International Test Solutions)*	
2:00 PM	**TUTORIAL (200 to 300PM)** Bond Pad Damage *Ken Karklin (Touchdown Technologies)* *and other committee members*	Statistical Process Control for the Sort Area *Darren Coil (Rudoph Technologies)*	On-line Cleaning Optimization to Extend Probe Card Technology Lifetime *James Tong (Texas Instruments)*	
2:30 PM		*ISMI Wafer Probe Council Team Activities & Industry Perspectives* *Boyd Daniels (Texas Instruments), Stu Crippen (Intel), Tom Wear (ISMI)*	Probe-tip Clean on Demand *Rob Marcelis (Salland Engineering)*	
3:00 PM	**BREAK (300 to 330PM)**	**BREAK (300 to 330PM)**	**BREAK (300 to 330PM)**	
3:30 PM	**Controlling Pad and Probe Card Damage (330 to 500PM)** Advanced Confocal Microscopy on a Process-Capable Platform *Eddy Robinson, Ph. D., (Hyphenated Systems)*	**Power and High Voltage (330 to 500PM)** Practical Considerations for Avalanche Testing of Power Semiconductor Wafers *Steven T. Clauter (Integrated Technology Corp.), Taichi Ukai (Taitech)*	**EXHIBITS OPEN + POSTER SESSION** **Sodas and Cookies will be served** **(300PM to 500PM)**	
4:00 PM	Achieving Tool-tool Correlation and Tool Stability for Probe Mark Inspection (PMI) in Automotive Applications *Rajiv Roy (Rudolph Technologies)*	"Under Pressure" - From High Voltage to MEMS Probing *Rainer Gaggl, Ph.D. (TIPS)*		
4:30 PM	Protecting Multi-DUI Probe Cards - A New Automated Visual Inspection Method Identifies Potentually Damaging Particles *Amir Giled (Camtek)*			
5:00 PM	**REGISTRATION and RECEPTION** **(400 to 700 PM)**	**PARADISE BALLROOM FOYER** **RECEPTION (500 to 600 PM)** **EXHIBITS OPEN** **CARVING STATION DINNER** **(500 to 800PM)**		
5:30 PM				
6:00 PM			**USS MIDWAY DINNER** **BUSES DEPART FOR USS MIDWAY AT 600PM** **(600 TO 1000PM)** **Reception, Dinner, Tours, Simulators, FUN !** and, of course, more NETWORKING	
6:30 PM				
7:00 PM	**BUFFET DINNER (700 to 815 PM)**			
7:30 PM				
8:00 PM	**PROBE YEAR IN REVIEW (815 to 900 PM)** **Jerry Broz, Ph.D. (SW Test General Chair)**	**Open for Any Vendor Sponsored Events** **Open for Any Sponsored Vendor Press Events**		
8:30 PM				
9:00 PM	**KEYNOTE (900 to 945 PM)** **Debbora Ahlgren** **Vice President & Chief Marketing Officer of Verigy** **Wafer Test Industries Impact on ATE**	**BAREFOOT BAR for NETWORKING**		
9:30 PM	**BAREFOOT BAR for NETWORKING**			
VER: 052208				

2008 SW Test Workshop
Preliminary Poster Program

	POSTER SESSION 01 TUESDAY (June 10, 2008)
P1_01	**CO2 Composite Spray Cleaning Technology for Probe Card Cleaning** David P. Jackson (Cool Clean Technologies)
P1_02	**Wafer Cleaning for Test Improvements** Terence Q. Collier (CVInc)
P1_03	**Unlocking the Mystery of Precision Inductors in High Volume Production RF Test Environments** Roger Hayward (Cascade Microtech)
P1_04	**Advanced Technology for High Parallelism Testing of Image Sensor Devices** Phill Mai (JEM America)
P1_05	**New Probe card Analyzer: OS Tester** Oscar Beijert (Beijert Engineering)
P1_06	**Implementing Tool Conversion Request (TCR) Protocol to Ensure the Effectiveness of Copper Contamination Control** Hasmayati Bakar (Silterra)

	POSTER SESSION 02 TUESDAY (June 10, 2008)
P2_01	**PCA Manager III System Accuracy and Repeatibility** Oscar Beijert (Beijert Engineering)
P2_02	**Comparison of Drilling Rates and Tolerances of Laser-Drilled holes in Silicon Nitride and Polyimide Vertical Probe Cards** Alan Ferguson, Ph. D. (Oxford Laser)
P2_03	**Automatic Probe Assembling Machine** JP Chun (TSE)
P2_04	
P2_05	
P2_06	

IEEE SW-Test Workshop
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